TOSHIBA PHOTOCOUPLER PHOTO RELAY

TLP199D

MEASUREMENT INSTRUMENTS

The TOSHIBA TLP199D consists of an infrared emitting diode optically coupled to a photo-MOS FET in a plastic SOP package.

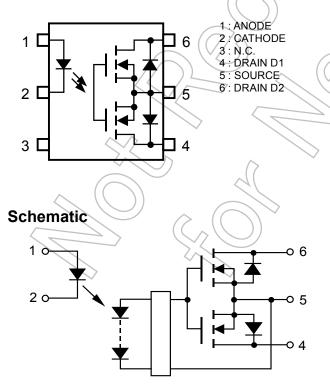
Its characteristics include low OFF-state current and low output pin capacitance, enabling it to be used in high-frequency measurement instruments.

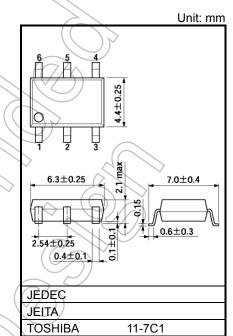
Features

- 6 pin SOP (2.54SOP6) : 2
- 1-Form-A
- Peak Off-State Voltage : 2
- Trigger LED Current
- On-State Current
- On-State Resistance
- Output Capacitance
- Isolation Voltage
 - UL-recognized
- cUL-recognized

- P6) : 2.1 mm high, 2.54 mm pitch
 - : 200 V (min)
 - : 3 mA (max)
 - : 50 mA (max)
 - : 50 Ω (max)
 - : 20 pF (max)
 - : 1500 Vrms (min)
 - : UL 1577, File No.E67349
 - : CSA Component Acceptance Service No.5A File No.E67349

Pin Configuration (Top View)





Weight: 0.13 g (typ.)

Absolute Maximum Ratings (Ta = 25°C)

$\begin{tabular}{ c c c c c } \hline Characteristics & Symbol Rating Unit \\ \hline Forward Current Derating (Ta $$ 25°C) & \Delta IF/°C & -0.5 & mA/°C \\ \hline Forward Current Derating (Ta $$ 25°C) & \Delta IF/°C & -0.5 & mA/°C \\ \hline Reverse Voltage & V_R & 5 & V \\ \hline Diode Power Dissipation Derating (Ta $$ 25°C) & \Delta P_D /°C & -0.5 & mW/°C \\ \hline Junction Temperature & T_j & 125 & °C \\ \hline Junction Temperature & T_j & 125 & °C \\ \hline Off-State Output Terminal Voltage & VOFF & 200 & V \\ \hline On-State Current & B Connection & ION & 50 & mA \\ \hline On-State Current Derating (Ta $$ 25°C) & \Delta IoN/°C & -0.5 & mA/°C \\ \hline On-State Current & A Connection & ION & 50 & mA \\ \hline On-State Current Derating & A Connection & 100 & -0.5 & mA/°C \\ \hline (Ta $$ 25°C) & A Connection & \Delta IoN/°C & -0.5 & mA/°C \\ \hline Output Power Dissipation & A Connection & 125 & mW \\ \hline \end{tabular}$							
$\begin{tabular}{ c c c c c c } \hline Forward Current Derating (Ta $$ 25°C) & $\Delta IF/°C & -0.5 & mA/°C$ \\ \hline \end{tabular} \hline t$	Characteristics			Symbol	Rating	Unit	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		Forward Current	lF	50	mA		
$\begin{array}{c c c c c c c c } \hline & & & & P_D & 50 & mW \\ \hline Diode Power Dissipation Derating (Ta \geq 25^{\circ}C) & \Delta P_D /^{\circ}C & -0.5 & mW /^{\circ}C \\ \hline Junction Temperature & & T_j & 125 & ^{\circ}C \\ \hline Junction Temperature & & & T_j & 125 & ^{\circ}C \\ \hline & & Off-State Output Terminal Voltage & VOFF & 200 & V \\ \hline & & & A Connection & & 50 & & & \\ \hline & & On-State Current & & B Connection & & & 100 & & & \\ \hline & & On-State Current Derating & & A Connection & & & & 100 & & & \\ \hline & & & & & & A Connection & & & & & & & & \\ \hline & & & & & & & & & &$	LED	Forward Current Derating (Ta	ΔIF/°C	-0.5	mA/°C		
$\frac{P_{OO}}{P_{OO}} = \frac{P_{OO}}{P_{OO}} = P_$		Reverse Voltage	VR	5	V		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		Diode Power Dissipation	PD	50	mW		
$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$		Diode Power Dissipation Der	ating (Ta ≥ 25°C)	ΔP _D /°C	-0.5	mW/°C	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		Junction Temperature		Tj	125	°C	\bigcirc
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		Off-State Output Terminal Vo	Voff	200	$\left(\sqrt{V} \right) \langle$		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $			A Connection		50		2
$\begin{array}{c c} & & & \\ \hline & On-State Current Derating \\ (Ta \ge 25^{\circ}C) \end{array} & \begin{array}{c} A \ Connection \\ \hline B \ Connection \\ \hline C \ Connection \\ \hline A \ Connection \\ \hline A \ Connection \\ \hline \end{array} & \begin{array}{c} -0.5 \\ \hline 0.5 \\ \hline -1.0 \\ \hline 125 \\ \hline \end{array} & \begin{array}{c} MA/^{\circ}C \\ \hline 125 \\ \hline \end{array} \end{array}$		On-State Current	B Connection	ION	50	mA	
$ \begin{array}{c c} & On-State Current Derating \\ (Ta \ge 25^{\circ}C) \end{array} & \hline B \ Connection \\ \hline C \ Connection \\ \hline A \ Connection \\ \hline A \ Connection \\ \hline C \ C \ Connection \\ \hline C \ C \ C \ C \ Connection \\ \hline C \ C \ C \ C \ C \ C \ C \ C \ C \ C$			C Connection		100	7	
$\begin{array}{c c} C \\ C $, i i i i i i i i i i i i i i i i i i i	A Connection		-0.5		
O UTPUT Power Dissipation C Connection A Connection 125 B Connection 52.5	К		B Connection	Δl _{ON} /°C	-0.5	> mA/°C	$\langle \rangle$
H H A Connection 125 H B Connection Po 52.5	CTC		C Connection		-1.0		52
B Connection Po 52.5 mW	Ĕ	Output Power Dissipation	A Connection		125	\sim	\bigcirc
	ä		B Connection	Po	52.5	mW	$\langle \langle U \rangle \rangle$
C Connection 105			C Connection	10	105	(
Output Power Dissipation A Connection -1.25		Output Power Dissipation	A Connection		-1.25		\sim
Derating B Connection $\Delta P_0 l^{\circ}C$ -0.525 mW+ $^{\circ}C$		Derating	B Connection	ΔP _o /°C	-0.525	m₩+°C	\mathcal{O}
(Ta ≥ 25°C) C Connection -1.05		(Ta \ge 25°C) C Connection			-1.05	775	
Junction Temperature		Junction Temperature	Tj	125			
Storage Temperature Range T _{stg} 55 to 125 °C	Storage Temperature Range			Tstg	-55 to 125	°C	
Operating Temperature Range Topr -40 to 85 °C	Operating Temperature Range			Topr	-40 to 85	°C	
Lead Soldering Temperature (10 s) T _{sol} 260 °C	Lead	Soldering Temperature (10 s)		T _{sol}	260	°C	
Isolation Voltage (AC, 60 s, R.H. ≤ 60 %) (Note 1) BVs 1500 Vrms	Isolat	tion Voltage (AC, 60 s, R.H. ≤	60 %) (Note 1)	BVs	1500	Vrms	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Device considered a two-terminal device: LED side pins are shorted together, and DETECTOR side pins are shorted together.

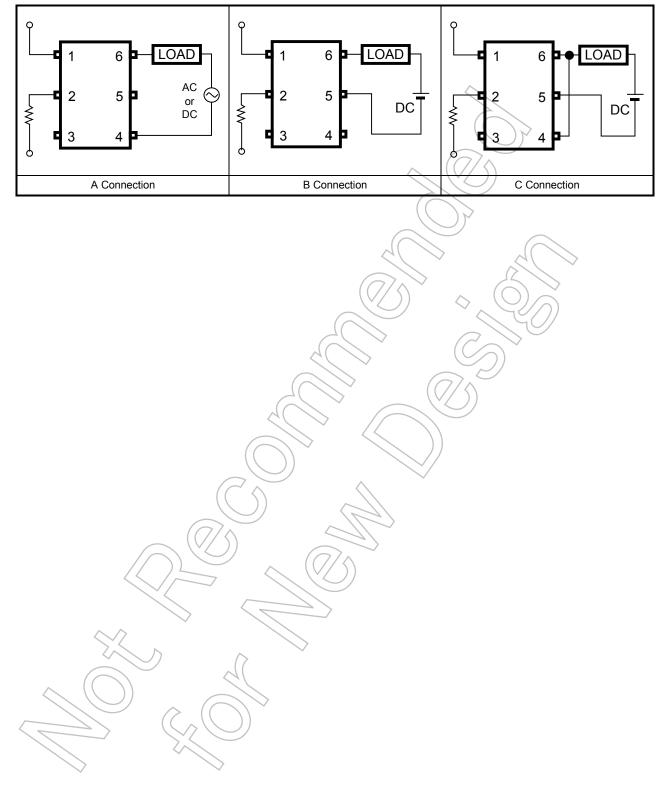
Recommended Operating Conditions

CHARACTERISTIC	SYMBOL	Min	Тур.	Max	UNIT
Supply Voltage	V _{DD}	_	_	160	V
Forward Current	lF	5	7.5	15	mA
On-State Current	ION	_	_	50	mA
Operating Temperature	T _{opr}	-20		60	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

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Circuit Connections



Electrical Characteristics (Ta = 25°C)

	Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
	Forward Voltage	VF	I _F = 10 mA	1.0	1.15	1.3	V
LED	Reverse Current	IR	V _R = 5 V	_	_	10	μA
	Capacitance	Ст	VF = 0 V, f = 1 MHz	Ý	30		pF
CTOR	Off-State Current	IOFF	V _{OFF} = 160 V	¢		1	nA
DETECTOR	Capacitance	COFF	V = 0 V, f = 1 MHz	$\overline{\mathbb{Z}}$	15	20	pF

Coupled Electrical Characteristics (Ta = 25°C)

Cha	racteristics	Symbol	Test Condition	Min	Тур.	Max	Unir
Trigger LED Cu	irrent	IFT	I _{ON} = 50 mA	_	21	3	mA
Return LED Cu	rrent	I _{FC}	loff = 100 μA	0.1 (\bigcirc	_	mA
	A Connection		I _{ON} = 50 mA, I _F = 5 mA	$\langle \rangle$	40	50	
On-State Resistance	B Connection	R _{ON}	I _{ON} = 50 mA, I _F = 5 mA	\mathcal{C}	30	40	Ω
	C Connection		I _{ON} = 100 mA, I _F = 5 mA	Y) 15	_	

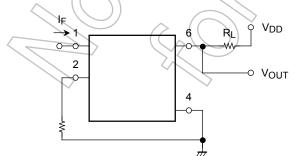
Isolation Characteristics (Ta = 25°C)

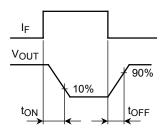
Characteristics	Symbol Test Condition	Min	Тур.	Max	Unit
Capacitance Input to Output	Cs Vs = 0 V, f = 1 MHz	—	0.8	—	pF
Isolation Resistance	Rs Vs = 500 V, R.H. ≤ 60 %	$5 imes 10^{10}$	10 ¹⁴	—	Ω
Isolation Voltage	BVs AC, 60 s	1500	_	_	Vrms

Switching Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Turn-on Time	ton	R _L = 200 Ω (Note 2) —	—	0.5	
Turn-off Time	tOFF	$V_{DD} = 10 \text{ V}, \text{ I}_{\text{F}} = 5 \text{ mA}$	_	_	0.2	ms







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